# MOHIT BHARDWAJ

Phone: (+1) 617-710-6302 Email: <a href="mailto:bhardwaj.m@northeastern.edu">bhardwaj.m@northeastern.edu</a>
Personal Website: <a href="mailto:https://www.linkedin.com/in/mohit-bhardwaj.20">https://www.linkedin.com/in/mohit-bhardwaj.20</a>
LinkedIn: <a href="mailto:https://www.linkedin.com/in/mohit-bhardwaj.20">https://www.mbhardwaj.com</a>

#### PERSONAL STATEMENT

Mechanical Engineer with 3+ years of industry experience. Currently working in the fast-paced and high-precision semiconductor industry at ASML, as Team Lead for an overlay measurement module (named YieldStar). My passions lie in product development from conceptualization to volume production, particularly in the field of robotics and automation. I consider myself detail oriented, innovative, and highly motivated.

#### **EDUCATION**

Northeastern University, Summa Cum Laude, Boston, MA, USA

May 2017

Bachelor of Science in Mechanical Engineering and Physics, Minor in Mathematics

GPA: 3.99

Honors/Awards: Presidential Global Fellowship, Senior Excellence in Research, Honors Program Activities: Member of NU Sail-bot (Robotic Sailboat Club), Society of Asian Scientists and Engineers

**International School of Lusaka**, Honorary Distinction, Lusaka, Zambia *International Baccalaureate Diploma Program* 

May 2012 GPA: 40/45

## PROFESSIONAL EXPERIENCE

ASML, Wilton, CT, USA

Oct 2019 - Current

Team Lead (TL) for YieldStar Module

- Manage a team of 18 design engineers; own the planning and execution of product deliverables which facilitate the shipment of new modules; successfully shipped 2 new modules during my time as TL
- Deconstruct customer requirements into specific design changes with key milestones, and delegate these across the team by optimizing resource allocation
- Align the cross-sector team (logistics, production, sourcing, and costing) to converge on design changes, and efficiently introduce design changes via the Engineering Change (EC) process

ASML, Wilton, CT, USA

Jul 2018 - Oct 2019

Team Lead (TL) for Ultra Violet Level Sensor (UVLS) Module

- Managed a team of 3 design engineers; owned planning and execution to address field escalations with the MK2 Module of the Level Sensor; successfully closed out over 20 escalations during my time as TL
- Optimized design changes by having regular one-on-one meetings with the designers and being a key stakeholder in all design reviews

ASML, Wilton, CT, USA

Sep 2017 - Jul 2018

Designer for Ultra Violet Level Sensor (UVLS) Module

- Applied precision engineering in design- such as pin and hole ISO standard tolerances, design of kinematic ball and v-groove mounts for optics and housings, and adjustable load-bearing stages- to obtain up to 0.1-micron level precision for optical measurements in opto-mechanical assemblies
- Enhanced CAD modeling skills in NX, including PMI dimensioning, deformation and stress FEA via Design Sim, and creating Technical Professional Drawings (TPDs) using General Standards of ASML

### Philips Color Kinetics, Burlington, MA, USA

July 2016 - Dec 2016

Product Design and Development Engineering Intern

Verified performance of designs through application driven prototyping, testing, and material selection;
 gained hands-on experience in 3D printing (FDM and Objet), laser cutting, welding, and CNC milling

# **ASML**, Eindhoven, the Netherlands

Sep 2015 - Dec 2015

Developmental Engineering Intern

Created testing protocols for various methods of air leak detection and localization (including ultrasound, infrared thermography, and tracer gas technologies); my findings reduced the system downtime by 25%

# Symbotic, Wilmington, MA, USA

July 2014 - Dec 2014

Robotics Research and Development Intern

 Built an agent based simulation of the next generation of autonomous robots used in warehouses to determine key statistics, such as bottlenecks and collisions in the system, and average robot idle time

#### **PROFICIENCIES**

Applications: NX, Enterprise Project, SolidWorks, AutoCAD, ANSYS, MS Office, C++, MATLAB

Languages: Fluent in English, Fluent in Hindi, Conversational Spanish

Hands-On Skills: 3D Printing, Laser Cutting, Set Molding, Machining (Lathe, Mill, Band-Saw)

# INTERESTS

Avid traveler (13 countries in counting); have summited Mount Kilimanjaro in Tanzania (7-day excursion)